

STT READOUT MEETING

25 MAY 2018 | PETER WINTZ

TOPICS TODAY



- Overview Decision Process
- General Readout Status
- System Completion & Resources

- Individual Status Reports (ADC)

- Discussion: Messages at next CM

- Finances & resources planning for STT & FT systems at Day 1 (2023) ongoing
- STT/FT status reports at CMs and to PANDA officials (Mar/Apr/May/June)

- STT system
 - Complete system set up for day 1 start
 - Open WPs identified (mech. system, gas system, ..)
 - Cost consolidation done (e.g. readout systems, synergies, ..)

- Decision about final STT readout will be done by PANDA-CB
 - Clear readout status reports, open points & next plans needed
 - Input from us for the decision
 - High transparency of decision wanted, solid ground for acceptance
 - Implications for PANDA experiment (FE-layout, PID performance, ..)
- Decision required in June/July

STT COST TABLE



- Requested by PANDA officials and reported at CM 18/1
- Further iteration ongoing (open WP, ..)
- Readout system cost table set up within the two working groups in February
 - Mainly production & installation & maintenance costs, no re-design

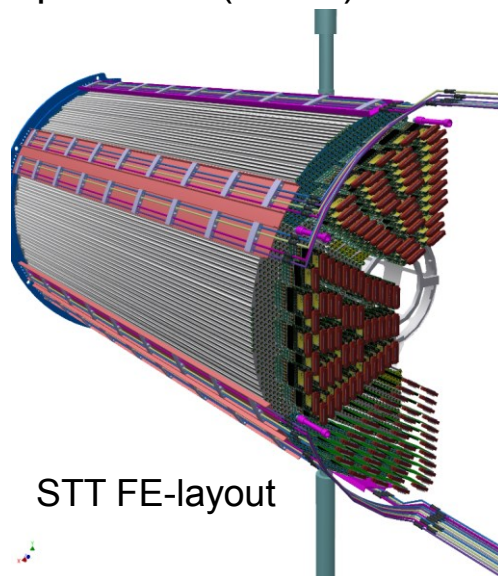
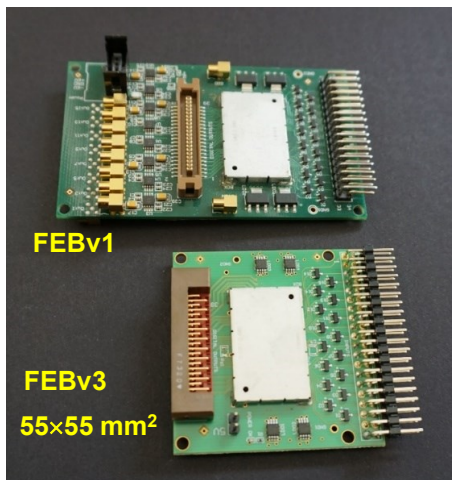
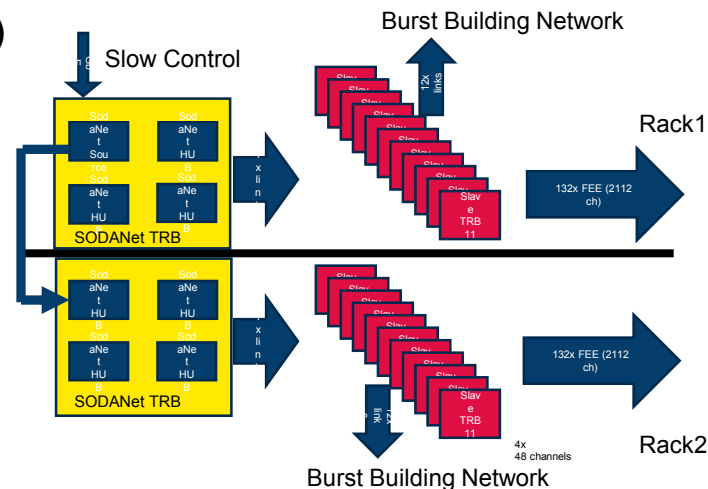
STT Work Package / Costs (T EUR)		Update (2018)		Risk	Synergy Savings		Responsible Institutions		
		RO #1	RO #2		FT	Phase0	FZJ	Krakow	IFIN
3	Electronic readout								
	3.1 ASIC/TRB	416		100					
	ASICv1/FEBv1-v3 Design	37		40					
	PASTTRECv1/FEBv3 (4800 ch)	41		20					
	FE-layout/cooling/HV-boards	50		40					
	Readout Board/Crate: TRB3, LVDS	78							
	Cable, data links	10							
	DataConcentrator	100							
	TRBx/DataConc for full lumi	100							
	ASIC/FPGA Maintenance/Lab	100			-75				
	3.2 ADC-based		650	100					
	Cables/HV-decoupling		180						
	Readout Board/Crate		400	100					
	Amp/ADC/FPGA/DataConc		70						
	FPGA Maintenance/Lab								

ASIC/TRB READOUT



- STT-specific ASIC “PASTTRECv1” (AGH & JU Krakow)
- FEBv3 for STT developed (small size, low power)
- TRB3 system with FPGA-ASIC control (SW)
- Data concentrator stage in progress (commercial HW)
- PID by time-over-threshold
- TRB3 integration into PANDA-DAQ (SODANet sync.)
- PANDA-DAQ (CN) set up: straws (TRB3) & EMC (ADC)

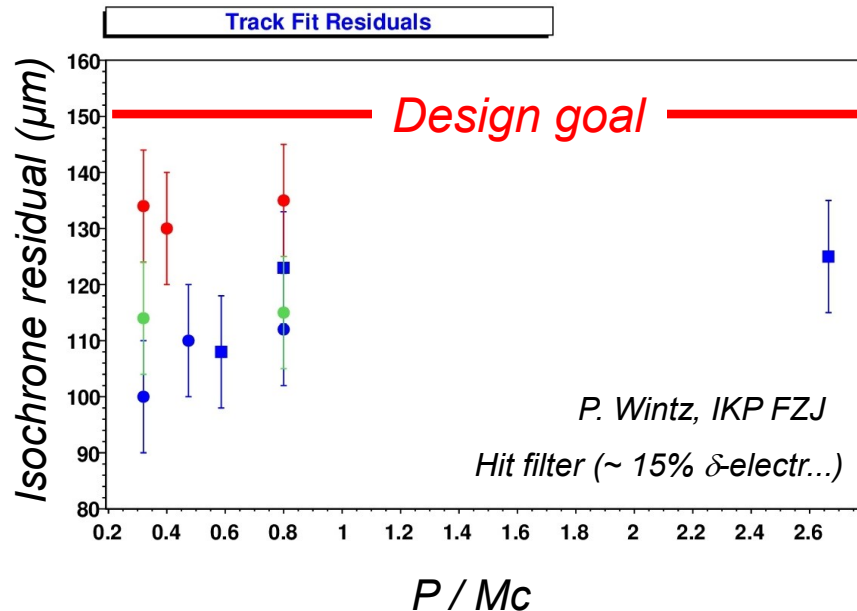
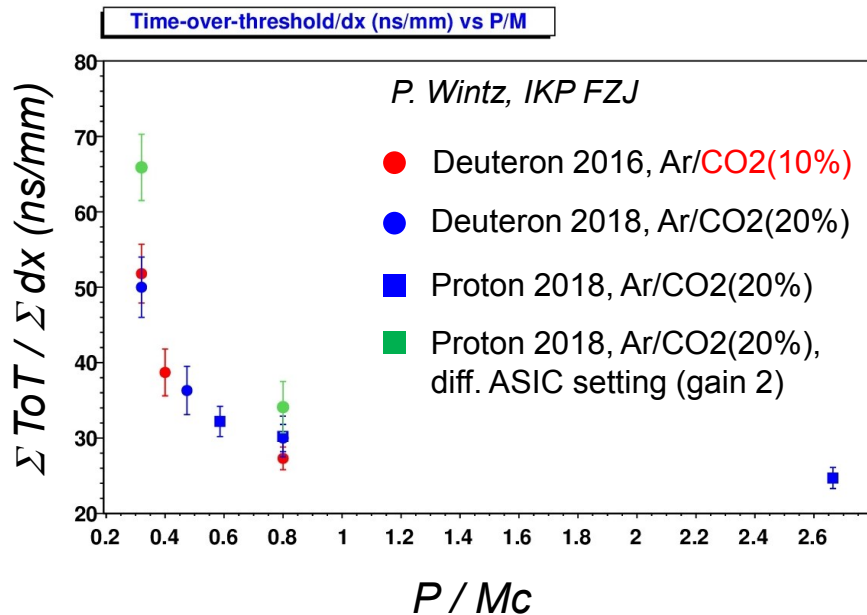
HARDWARE SETUP



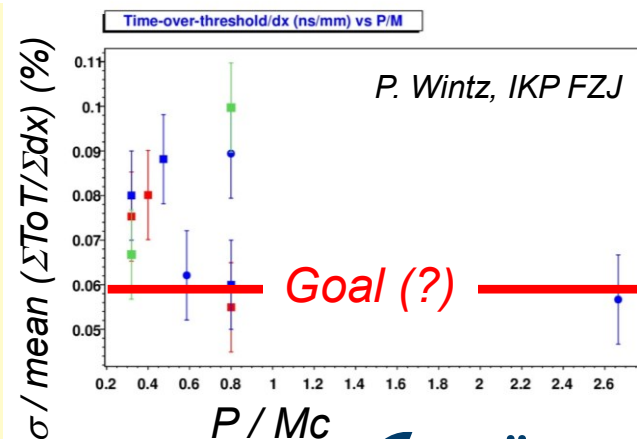
Straw (256ch, TRB3) & EMC (3x3 crystals, ADC) & PANDA-DAQ (3 CN) test setup in Krakow



TESTBEAM RESULTS ASIC/TRB

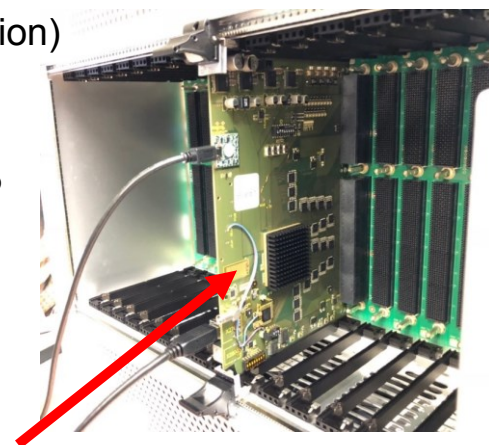


- ToT results (deuteron, proton beam & cosmics)
 - S ~ 3.3 (K/p @ 750 MeV/c, TDR: S ~ 5)
 - S ~ 5 (K/p @ 390 MeV/c, TDR: S ~ 8)
 - S ~ 9 (π /p @ 300 MeV/c, TDR: S ~ 13)
- All TDR separation power w/ 10% dE/dx resolution
- ~ 60-70% of TDR separation power reached by ToT
- But: low truncation yet, can treat results as lower limits



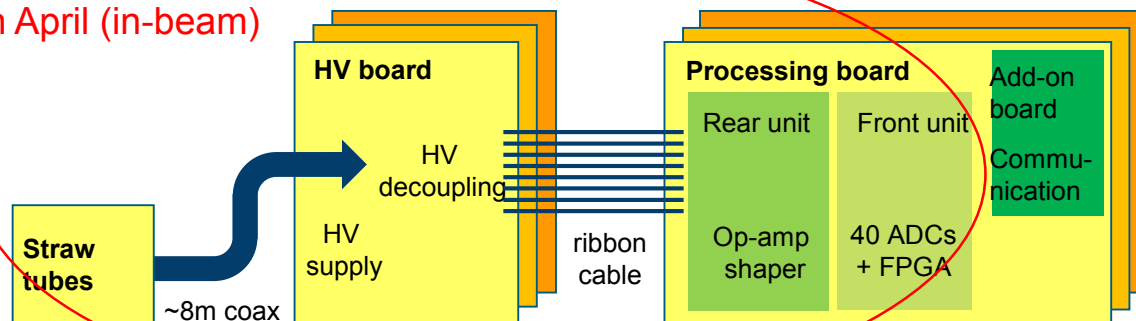
ADC-BASED READOUT

- STT-specific, non-standard scheme: “frontend electronics-free“
 - HV & signal on same coax line, straw access from backend (cut off option)
 - FE-layout: no cooling, low mat. budget, less space required
- RO board design by FZJ/ZEA-2, system scheme by IFJ PAN/IKP
 - Op-amps, waveform sampling ADC (40× 4 ch @ 160 MSPS, 12 bit)
 - WF-readout & signal processing by central FPGA (Xilinx Virtex7)
- Data concentrator stage as Add-on board (hit sorting)

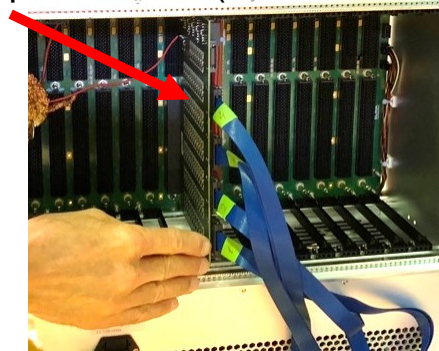


160ch readout board, double-sided, with 2x20 ADC, 1x central FPGA (crate front side)

Components tested in April (in-beam)

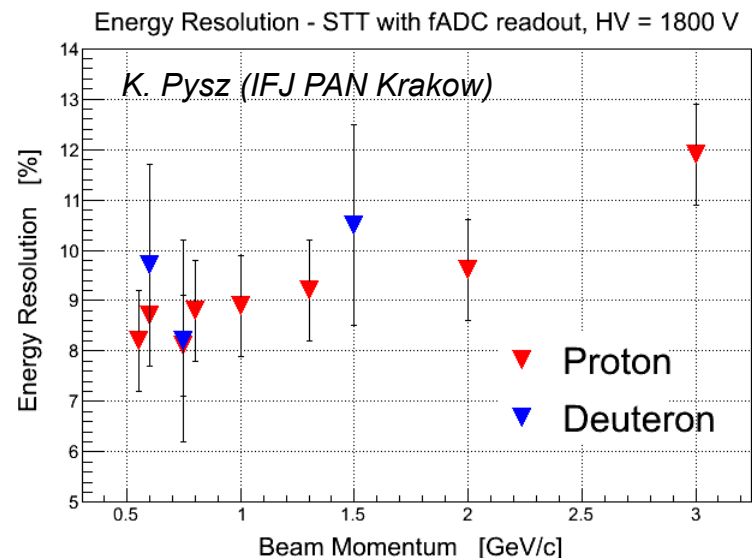
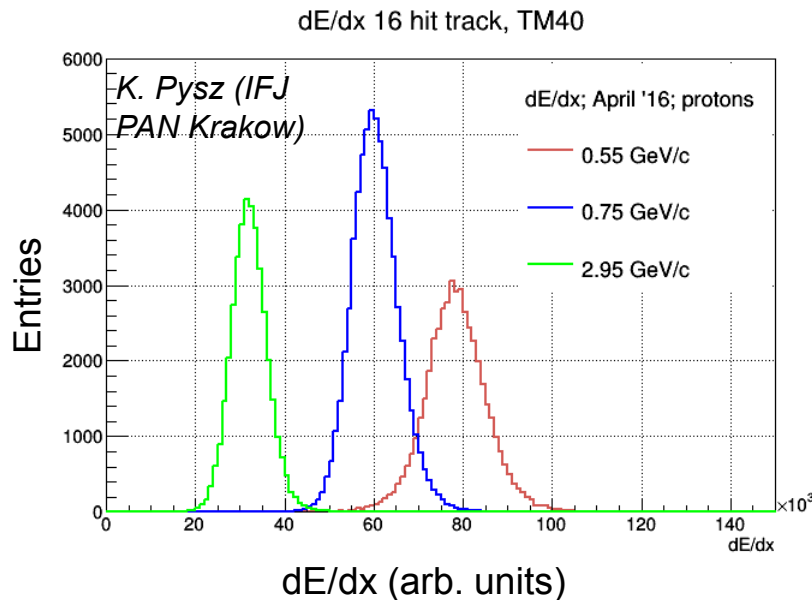


160ch amplifier board (crate rear side)



TESTBEAM RESULTS ADC-SYSTEM

- Results for FADC (240 MHz) prototype system (and direct straw cabling)
- Raw mode readout with full WF information, no real-time FPGA pulse analysis
 - Example: separation of 2.95/0.55 GeV/c protons: $S \sim 8.5$
 - Treat prelim. results of S as upper limit (?)
- New SADC (160 MHz, 12 bit), Op-Amp board brought into operation in April
 - ToDo: Op-amp dynamic range to be tested (5-50 keV/cm)
 - ToDo: real-time FPGA readout, data stream output (HW)



SYSTEM COMPLETION ESTIMATE



ASIC/TRB3 Readout

Remaining WP list	(min.) Resources (FTE/a)
• FE-mech. layout / cooling, HV distr., cable routing scheme	1
• Data concentrator stage (HW selected) & PANDA-DAQ integration	0.5
• Real-time FPGA programming (hit sorting, data concentr., tracking, ..)	0.5
• ASIC, FE-board & FPGA maintenance, design & test lab	1.5
• Tracking & PID SW algorithms (offline), test data analysis	0.5
• Total: ~ 4 FTE/a + (>) 2 PhD	
• ~ -1 FTE synergy with Forward Tracker (ASIC/FPGA/DAQ)	
• TRBx for phase 3, additional cost incorporated in cost/resource table	
• TRB3 & PANDA-DAQ (CN) test system set up, in-beam tests next (straws & EMC)	
• STS@HADES setup, ~1800 channel ASIC/TRB3 system under exp. conditions	

ADC-based Readout

Remaining WP list

(min.) Resources (FTE/a)

- Analog signal part, final cable routing / hv-supply, installation 1
- Final Amp/ADC board design & production 0.5
- ➔ • Communic. board design & production, PANDA-DAQ integration 0.5
- ➔ • WF processing and readout in real-time (FPGA) 0.5
- ➔ • Pre-series system set up, testbeam measurements 1
- Real-time FPGA programming (hit sorting, data concentr., tracking, ..) 0.5
- System HW & FPGA maintenance, design & test lab 1
- Tracking & PID SW algorithms (offline), test data analysis 0.5

- **Total: ~ 5.5 FTE/a + (>) 2 PhD**

- ~ 1 more year (x 4.5 FTE) for completion & commissioning of pre-series system
- ~ 2 weeks testbeam time with dE/dx range 5-50 keV/cm

GENERAL REMARKS



- Spatial (isochrone) resolution better than design goal ($\sigma = 150\mu\text{m}$) expected for both readouts, same calibration & tracking methods
- PID capability demonstrated for both readouts by in-beam tests
- Better PID expected for ADC (pulse area \leftrightarrow pulse width), but to be demonstrated in-beam over full dE/dx range (pulse shape distortion by amp/shaper expected)
- FTEs for work packages not (fully) assigned, Eols of institutions existing (partly)
- **MoUs required to establish WP planning** towards STT installation
- Manpower situation critical, remains challenging (staff & students)
- Lab capacities critical (personnel)
- Experience loss instead of experience build-up, continuation of WP difficult
- Additional outsourcing of WPs might be required (e.g. cabling, solder work, ..)
- Temporary personnel to be set up (student courses, ..)

DISCUSSION

